

GUIDELINE 74

GROUNDING, BONDING, AND SHIELDING

1. Purpose. This guideline establishes grounding, bonding, and shielding interface criteria for installation of electronic equipment.

2. Applicable documents. The documents listed below are not necessarily all of the documents referenced herein, but are those needed to understand the information provided by this handbook.

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| MIL-STD-188-124 | Grounding, Bonding, and Shielding for Common Long Haul/Tactical Communication Systems Including Ground Based Communications-Electronics Facilities and Equipments. |
| MIL-STD-464 | Interface Standard for Electromagnetic Environmental Effects Requirements for Systems. |
| MIL-STD-1310 | Shipboard Bonding, Grounding, and Other Techniques for Electromagnetic Compatibility and Safety. |
| MIL-STD-1542 | Electromagnetic Compatibility (EMC) and Grounding Requirements for Space System Facilities. |
| MIL-HDBK-419 | Ground, Bonding, and Shielding for Electronic Equipments and Facilities. |
| MIL-HDBK-1857 | Grounding, Bonding, and Shielding Design Practices. |

3. Definitions. This section not applicable to this guideline.

4. General guidelines.

4.1 Provisions. Grounding, bonding, and shielding provisions should be incorporated into equipment design, as necessary, to enable installation of equipment into the applicable platform or facility. The grounding, bonding, and shielding installation and interface requirements are specified in the following documents:

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| Aerospace ground support facilities | MIL-STD-464 |
| Aircraft and space vehicles | MIL-STD-464 |
| Ground telecommunications C-E equipment | MIL-STD-188-124 |
| Shipboard equipment | MIL-STD-1310 |
| Ground space systems facilities | MIL-STD-1542 |
| Other Army ground equipment | MIL-HDBK-1857 |

4.2 Other Guidance. Guidance for grounding, bonding, and shielding may be found in MIL-HDBK-419.

5. Detail guidelines. This section not applicable to this guideline.